

Patent No. 4066 D1/Consilium/DV

PATENT/OFFICIAL

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of

John F. ARACKAPARAMBIL et al.

Serial No. 10/084,092

Filed: February 28, 2002

For: COMPUTER INTEGRATED MANUFACTURING TECHNIQUES

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Group Art Unit: 2121

Examiner:

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**INFORMATION DISCLOSURE STATEMENT**

Honorable Commissioner for Patents  
Washington, D.C. 20231

Sir:

In accordance with the provisions of 37 C.F.R. 1.56, 1.97 and 1.98, the attention of the Patent and Trademark Office is hereby directed to the documents listed on the attached form PTO-1449. It is respectfully requested that the documents be expressly considered during the prosecution of this application, and that the documents be made of record therein and appear among the "References Cited" on any patent to issue therefrom. Copies of the references listed on pages 1 and 2 of Form PTO-1449 are submitted herewith.

This Information Disclosure Statement is being filed within three months of the U.S. filing date OR before the mailing date of a first Office Action on the merits. No certification or fee is required.

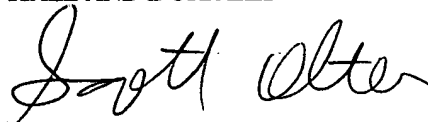
The references listed on Sheet Nos. 4 through 6 of Form PTO-1449 were cited by or submitted to the U.S. Patent and Trademark Office in parent application Serial No. 09/363,966, filed July 29, 1999, which is relied upon for an earlier filing date under 35 USC § 120. Copies of these references are not attached under 37 CFR 1.98(d).

This submission does not constitute a representation that a search has been made or that no better art exists and does not constitute an admission or representation that any of the listed documents is material or constitutes prior art. If it should be determined that any of the listed documents does not constitute prior art under the United States law, Applicants reserve the right to present to the Office the relevant facts and law regarding the appropriate status of such document.

No certification or fee is believed to be required. However, the Commissioner is hereby authorized to charge any additional fees should any be required for this submission, or credit any overpayment to deposit account no. 08-0219.

Respectfully submitted,

HALE AND DORR LLP

A handwritten signature in black ink, appearing to read "Scott M. Alter", written in a cursive style.

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**U.S. PATENT DOCUMENTS**

EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
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**FOREIGN PATENT DOCUMENTS**

EXAMINER'S INITIALS	PATENT NO./ PUBLICATION NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
	2,050,247	08/29/91	Canada			X	
	2,165,847	08/29/91	Canada			X	
	2,194,855	08/29/91	Canada			X	
	05-151231	06/18/93	Japan				X
	05-216896	08/27/93	Japan				X
	05-266029	10/15/93	Japan				X
	06-110894	04/22/94	Japan				X
	06-176994	06/24/94	Japan				X
	06-252236	09/09/94	Japan				X
	06-260380	09/16/94	Japan				X
	1072967A3	11/21/01	Europe			X	

**OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)**

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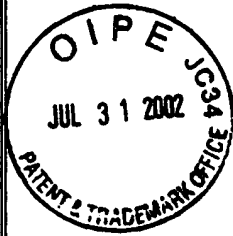
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	08-149583	11/15/89	Japan			X	
	09-34535	02/07/97	Japan			X	
	0877308 A2	11/11/98	Europe			X	
	11-67853	03/09/99	Japan			X	


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	Runyan, W. R., and K. E. Bean. 1990. "Semiconductor Integrated Circuit Processing Technology." pg. 48. Reading, Massachusetts: Addison-Wesley Publishing Company.

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	Zorich, Robert. 1991. <i>Handbook of Quality Integrated Circuit Manufacturing</i> . pp. 464-498 San Diego, California: Academic Press, Inc.						
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	Van Zant, Peter. 1997. <i>Microchip Fabrication: A Practical Guide to Semiconductor Processing</i> . Third Edition, pp. 472-478. New York, New York: McGraw-Hill.						
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